

	Type	Hits	Search Text	DBs	Time Stamp
1	IS&R	3494	(438/106,108,614).CCLS.	USPAT	2008/05/30 19:26
2	BRS	1574	S28 and @ad<"20010330"	USPAT	2008/05/30 19:26
3	IS&R	4670	(438/106,108,614).CCLS.	US-PGPUB; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	2008/05/30 19:26
4	BRS	2452	S30 and @ad<"20010330"	US-PGPUB; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	2008/05/30 19:26
5	IS&R	4229	(257/678,778,781).CCLS.	USPAT	2008/05/30 19:28
6	BRS	2081	S32 and @ad<"20010330"	USPAT	2008/05/30 19:28
7	IS&R	3384	(257/678,778,781).CCLS.	US-PGPUB; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	2008/05/30 19:29
8	BRS	958	S34 and @ad<"20010330"	US-PGPUB; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	2008/05/30 19:29
9	IS&R	5121	(257/E21.503,E21.508,E21.511,E23.021).CCLS.	USPAT	2008/05/30 19:35
10	BRS	2828	S36 and @ad<"20010330"	USPAT	2008/05/30 19:36
11	BRS	1744	S37 NOT (S29 OR S33)	USPAT	2008/05/30 19:36

	Type	Hits	Search Text	DBs	Time Stamp
12	IS&R	5200	(257/E21.503,E21.508,E21.511,E23.021),CCLS.	US-PGPUB; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	2008/05/30 19:39
13	BRS	1041	S39 and @ad<"20010330"	US-PGPUB; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	2008/05/30 19:39
14	BRS	886	S40 NOT (S31 OR S35)	US-PGPUB; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	2008/05/30 19:40
15	BRS	3070	(chip die) and (packag\$4) and (wafer) and (substrate) and (ball bump) and (join\$4) and (separat\$4 cut\$4 saw\$4)	USPAT	2008/05/30 19:42
16	BRS	236	((packag\$4) and ((separat\$4 singulat\$4 cut\$4 saw\$4) with (wafer) with (chip die)) and ((separat\$4 singulat\$4 cut\$4 saw\$4) with (substrate) with (open\$4 hole contact via)) and (ball bump) and (join\$4)	USPAT	2008/06/05 10:02
17	BRS	183	((packag\$4) and ((separat\$4 singulat\$4 cut\$4 saw\$4) with (wafer) with (chip die)) and ((separat\$4 singulat\$4 cut\$4 saw\$4) with (substrate) with (opening hole contact via)) and (ball bump) and (join\$4)	US-PGPUB; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	2008/06/05 10:46
18	BRS	18	((packag\$4) and ((separat\$4 singulat\$4 cut\$4 saw\$4) and (wafer) and (chip die)) and (substrate) and (opening hole contact via) and (ball bump) and (join\$4)).clm.	US-PGPUB	2008/06/05 11:43